WHAT IS CLAIMED IS:

1. A method of manufacturing a semiconductor structure, the method comprising:

providing a semiconductor substrate or substrate assembly; providing a precursor composition comprising one or more complexes of the formula:

[(R¹)NC(R²)C(R³)N(R⁴)]_xML_y

wherein:

M is a Group IVB, VB, or VIB metal; each R¹, R², R³, and R⁴ group is independently H or an

organic group;

L is selected from the group of CO, NO, CN, CS, CNR5,

R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is

independently an organic/group;

x = 1 to 4; and

y = 1 to 4; and

forming a metal-containing film from the precursor composition on a surface of the semiconductor substrate or substrate assembly.

- 2. The method of claim 1 wherein the step of forming a metal-containing film comprises vaporizing the precursor composition and directing it toward the semiconductor substrate or substrate assembly using a chemical vapor deposition technique.
- 3. The method of claim 2 wherein the chemical vapor deposition technique comprises flash vaporization, bubbling, microdroplet formation, or combinations thereof.

- 4. The method of claim 2 wherein the precursor composition is vaporized in the presence of a carrier gas.
- 5. The method of claim 2 wherein the precursor composition is vaporized in the presence of a reaction gas.
- 6. The method of claim 5 wherein the reaction gas is selected from the group of H₂, SiH₄, Si₂H₆, NH₃, N₂H₄, PH₃, AsH₃, GeH₄, t-BuSbMe₂, H₂S, H₂Se, Te(allyl)₂, and combinations thereof.
- 7. The method of claim 1 wherein each R^1 , R^2 , R^3 , and R^4 group is independently H or a (C_1-C_{30}) organic group.
- 8. The method of claim 1 wherein the complex is a monomer.
- 9. The method of claim 1 wherein each R, R², R³, and R⁴ group is independently H or a (C₁-C₄)alkyl moiety.
- 10. The method of claim 1 wherein R⁷ is cyclopentadienyl or a substituted cyclopentadienyl.
- 11. The method of claim 1 wherein the precursor composition is a liquid.
- 12. The method of claim 1 wherein the metal is a Group VB metal.
- 13. The method of claim 12 wherein the metal is vanadium.
- 14. The method of claim 1 wherein the metal-containing film is a Group IVB, VB, or VIB metal alloy film.

15. A method of forming a film on a substrate, the method comprising:

providing a substrate;

providing a precursor composition comprising one or more complexes of the formula:

$$[(R^1)NC(R^2)C(R^3)N(R^4)]_xML_y$$

wherein:

M is a Group IVB, VB, or VIB metal;

each R¹, R², R³, and R⁴ is independently H or an organic

group;

L is selected from the group of CO, NO, CN, CS, CNR⁵,

R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is

independently an organic group

x = 1 to 4; and

y = 1 to 4 and

forming a metal-containing film from the precursor composition on a surface of the substrate.

- 16. The method of claim 15 wherein the step of forming a metal-containing film comprises vaporizing the precursor composition and directing it toward the substrate using a chemical vapor deposition technique.
- 17. The method of claim 14 wherein the precursor composition is liquid.
- 18. A chemical vapor deposition system comprising:
 - a deposition chamber having a substrate positioned therein;
 - a vessel containing a precursor comprising one or more complexes of the formula:

$$[(R^1)NC(R^2)C(R^3)N(R^4)]_xML_y$$

wherein:

M is a Group IVB, VB, or VIB metal; each R^1 , R^2 , R^3 , and R^4 is independently H or an organic group;

L is selected from the group of CO, NO, CN, CS, CNR⁵, R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is independently an organic group;

x = 1 to 4; and

y = 1 to 4; and

a source of an inert carrier gas for transferring the precursor to the chemical vapor deposition chamber.

19. A chemical vapor deposition system comprising:

a deposition chamber having a substrate positioned therein; a vessel containing a precursor composition comprising one or more complexes of the formula:

$$[(R^1)NC(R^2)C(R^3)N(R^4)]_xML_y$$

wherein:

M is a Group IVB, VB, or VIB metal; each R¹, R², R³, and R⁴ is independently H or an organic group; each L is independently CO, NO, CN, CS, CNR⁵, R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is independently an organic group;

x = 1 to 4; andy = 1 to 4.

- 20. The system of claim 19 wherein the deposition chamber is adapted for forming a metal-containing film comprising vaporizing the precursor composition and directing it toward the semiconductor substrate or substrate assembly using a chemical vapor depositional technique.
- 21. The system of claim 20 wherein the chemical vapor deposition technique comprises flash vaporization, bubbling, microdroplet formation, or combinations thereof.
- 22. The system of claim 20 wherein the precursor composition is vaporized in the presence of a carrier gas.
- 23. The system of claim 20 wherein the precursor composition is vaporized in the presence of a reaction gas.

- 24. The system of claim 23 wherein the reaction gas is selected from the group of H₂, SiH₄, Si₂H₆, NH₃, N₂H₄, PH₃, AsH₃, GeH₄, t-BuSbMe₂, H₂S, H₂Se, Te(allyl)₂, and combinations thereof.
- 25. The system of claim 19 wherein each R¹, R², R³, and R⁴ group is independently H or a (C₁-C₃₀)organic group.
- 26. The system of claim 19 wherein the complex is a monomer.
- 27. The system of claim 19 wherein each R¹, R², R³, and R⁴ group is independently H or a (C₁-C₄)alkyl moiety.
- 28. The system of claim 19 wherein R⁷ is cyclopentadienyl or a substituted cyclopentadienyl.
- 29. The system of claim 19 wherein the precursor composition is a liquid.
- 30. The system of claim 19 wherein the metal is a Group VB metal.
- 31. The system of claim 30 wherein the metal is vanadium.
- 32. The system of claim 19 wherein the metal-containing film is a Group IVB, VB, or VIB metal alloy film.
- 33. A chemical vapor deposition system comprising:
 - a deposition chamber having a semiconductor substrate or substrate assembly positioned therein;
 - a vessel containing a precursor composition comprising one or more complexes of the formula:

$$[(R^1)NC(R^2)C(R^3)N(R^4)]_xML_y$$

wherein:

M is a Group IVB, VB, or VIB metal; each R¹, R², R³,and R⁴ is independently H or an organic group; each L is independently CO, NO, CN, CS, CNR⁵, R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is independently an

organic group; x = 1 to 4; and

y = 1 to 4.

- 34. The system of claim 33 wherein each R^1 , R^2 , R^3 , and R^4 is independently H or a (C_1-C_{30}) organic group.
- 35. The system of claim 33 wherein the complex is a monomer.
- 36. The system of claim 33 wherein each R^1 , R^2 , R^3 , and R^4 group is independently H or a (C_1-C_4) alkyl moiety.
- 37. The system of claim 33 wherein R⁷ is cyclopentadienyl or a substituted cyclopentadienyl.
- 38. A chemical vapor deposition system comprising:

a deposition chamber having a semiconductor substrate or substrate assembly positional therein;

a vessel containing a precursor composition comprising one or more liquid complexes of the formula:

$$[(R^1)NC(R^2)C(R^3)N(R^4)]_x ML_y$$

wherein:

M is a Group IVB, VB, or VIB metal; each R^1 , R^2 , R^3 , and R^4 independently H or a (C_1 -

C₃₀)organic group;

each L is independently CO, NO, CN, CS, CNR⁵, R⁶CN, or R⁷, wherein each R⁵, R⁶, and R⁷ group is independently an organic group;

x = 1 to 4; and

y = 1 to 4.